

### 62mm Half Bridge IGBT Module

$V_{CES} = 1700V$ ,  $I_C = 200A$ ,  $V_{CE(sat)} = 1.93V$

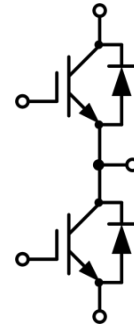
#### Features

- 1700V Trench/Field Stop Technology
- Low switching losses
- $V_{cesat}$  has a positive temperature coefficient



#### Applications

- Power Converters
- Uninterruptible power supplies
- Servo Drives
- Inverter



### IGBT, Inverter Maximum Ratings

Parameter	Symbol	Test Condition	Value	Unit
Collector-Emitter voltage	$V_{CES}$	$T_{vj}=25^{\circ}C$	1700	V
Continuous DC collector current	$I_{C\ nom}$	$T_C=100^{\circ}C$ , $T_{vj\ max}=175^{\circ}C$	200	A
Repetitive peak collector current	$I_{CRM}$	$t_p=1ms$	400	A
Total power dissipation	$P_{tot}$	$T_C=25^{\circ}C$ , $T_{vj\ max}=175^{\circ}C$	1250	W
Gate-Emitter voltage	$V_{GE}$		$\pm 20$	V

### Characteristics Values

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Collector-Emitter saturation voltage	$V_{CESat}$	$V_{GE}=15V$ , $I_C=200A$ $V_{GE}=15V$ , $I_C=200A$ $V_{GE}=15V$ , $I_C=200A$	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	1.93 2.22 2.39	2.50	V
Gate-Emitter threshold voltage	$V_{GE(th)}$	$I_C=8mA$ , $V_{GE}=V_{CE}$	$T_{vj}=25^{\circ}C$	5.10	5.70	6.30
Internal gate resistor	$R_{Gint}$			2.58		$\Omega$
Gate charge	$Q_G$	$V_{GE}=-15V \dots +15V$		1.90		$\mu C$
Input capacitance	$C_{ies}$	$f=1MHz$ , $V_{CE}=25V$ , $V_{GE}=0V$	$T_{vj}=25^{\circ}C$	27.18		nF
Reverse transfer capacitance	$C_{res}$			0.80		
Collector-emitter cut-off current	$I_{CES}$	$V_{CE}=1700V$ , $V_{GE}=0V$	$T_{vj}=25^{\circ}C$		2	mA
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V$ , $V_{GE}=20V$	$T_{vj}=25^{\circ}C$		200	nA
Turn-on delay time	$t_{d\ on}$	$I_C=200A$ , $V_{CE}=900V$ $V_{GE}=\pm 15V$ , $R_G=3.3\Omega$ (inductive load)	$T_{vj}=25^{\circ}C$	194		ns
			$T_{vj}=125^{\circ}C$	212		
			$T_{vj}=150^{\circ}C$	224		

Rise time	$t_r$	$I_C=200A, V_{CE}=900V$ $V_{GE}=\pm 15V, R_G=3.3\Omega$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		51 55 57		
Turn-off delay time	$t_{d\ off}$	$I_C=200A, V_{CE}=900V$ $V_{GE}=\pm 15V, R_G=3.3\Omega$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		430 489 506		
Fall time	$t_f$	$I_C=200A, V_{CE}=900V$ $V_{GE}=\pm 15V, R_G=3.3\Omega$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		303 352 368		
Turn-on energy loss per pulse	$E_{on}$	$I_C=200A, V_{CE}=900V$ $V_{GE}=\pm 15V, R_G=3.3\Omega$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		31.88 40.73 43.77		mJ
Turn-off energy loss per pulse	$E_{off}$	$I_C=200A, V_{CE}=900V$ $V_{GE}=\pm 15V, R_G=3.3\Omega$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		38.04 46.56 49.29		
SC data	$I_{SC}$	$V_{GE}\leq 15V, V_{CC}=1000V$ $V_{CEmax}=V_{CES}-L_{sCE}\cdot di/dt\ t_p\leq 10\mu s,$ $T_{vj}=150^\circ C$			1230		A
Thermal resistance, junction to case	$R_{thJC}$	per IGBT				0.12	K/W
Temperature under switching conditions	$T_{vj\ op}$			-40		150	$^\circ C$

### Diode, Inverter Maximum Ratings

Parameter	Symbol	Test Condition	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$	$T_{vj}=25^\circ C$	1700	V
Continuous DC forward current	$I_F$		200	A
Repetitive peak forward current	$I_{FRM}$	$t_p=1ms$	400	A
$I^2t$ -value	$I^2t$	$t_p=10ms, \sin 180^\circ, T_{vj}=125^\circ C$	10000	A <sup>2</sup> s

### Characteristics Values

Parameter	Symbol	Test Condition	Value			Unit	
			Min.	Typ.	Max.		
Forward voltage	$V_F$	$I_F=200A, V_{GE}=0V$ $I_F=200A, V_{GE}=0V$ $I_F=200A, V_{GE}=0V$		$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	2.07 2.28 2.24	2.50	V
Peak reverse recovery current	$I_{RM}$	$I_F=200A$ $-diF/dt=2430A/\mu s(T_{vj}=150^\circ C)$ $V_R=900V, V_{GE}=-15V$		$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	109 122 122		A
Recovered charge	$Q_r$	$I_F=200A$ $-diF/dt=2430A/\mu s(T_{vj}=150^\circ C)$ $V_R=900V, V_{GE}=-15V$		$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	22.80 38.70 39.90		$\mu C$
Reverse recovered energy	$E_{rec}$	$I_F=200A$ $-diF/dt=2430A/\mu s(T_{vj}=150^\circ C)$ $V_R=900V, V_{GE}=-15V$		$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	12.70 23.07 23.26		mJ
Thermal resistance, junction to case	$R_{thJC}$	per diode				0.16	K/W
Temperature under switching conditions	$T_{vj\ op}$			-40		150	$^\circ C$

### Characteristics Values(Module)

Parameter	Symbol	Test Condition	Value	Unit	
Isolation test voltage	$V_{ISOL}$	RMS, f=50Hz, t=1min	4000	V	
Internal isolation			Al <sub>2</sub> O <sub>3</sub>		
Storage temperature	$T_{stg}$		-40	125	°C
Mounting torque for module mounting	M		3.0	6.0	Nm
Weight	W		318		g

### Typical Characteristics

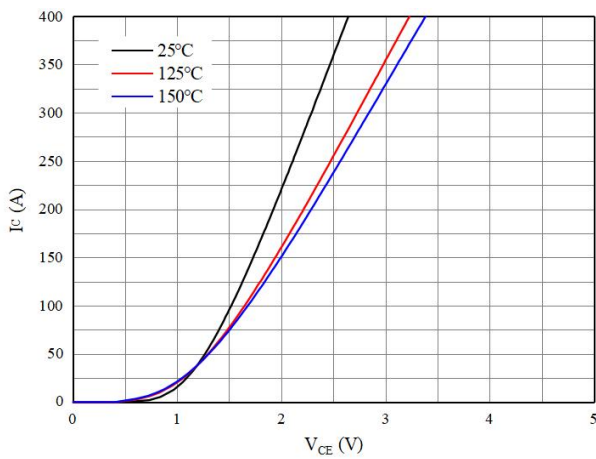


Fig 1. Typical output characteristics ( $V_{GE}=15V$ )

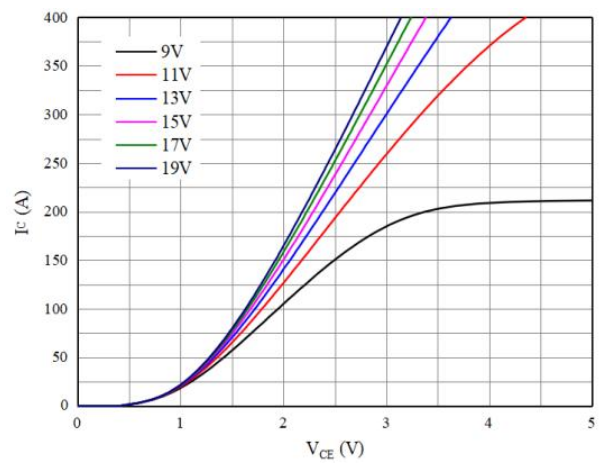


Fig 2. Typical output characteristics ( $T_{vj}=150^{\circ}C$ )

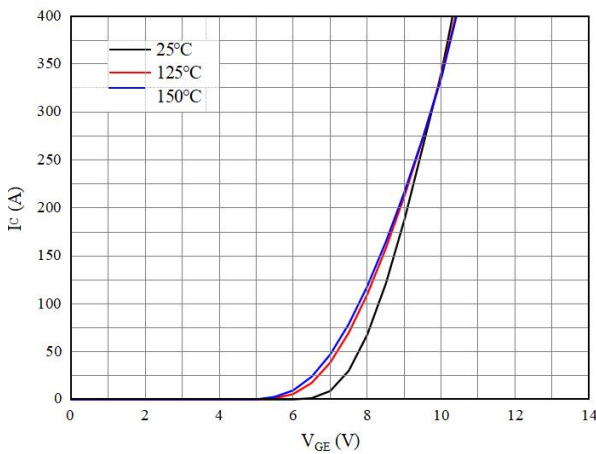


Fig 3. Typical transfer characteristic( $V_{CE}=20V$ )

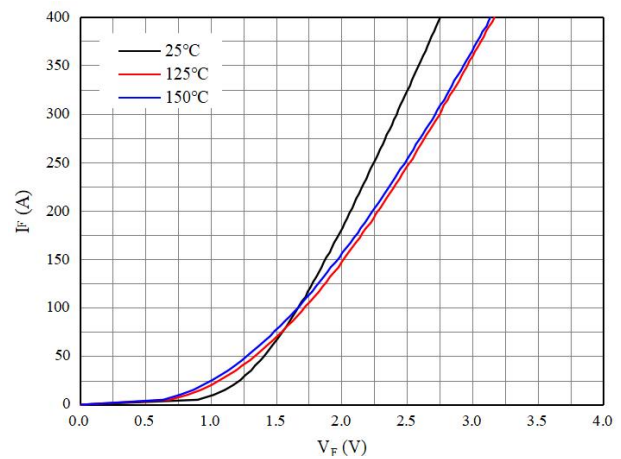


Fig 4. Forward characteristic of Diode

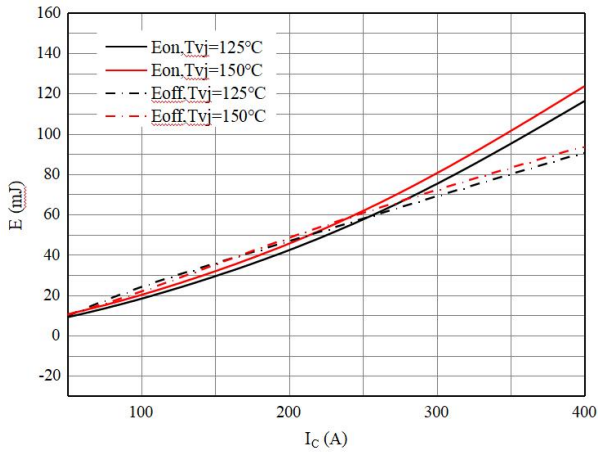


Fig 5. Switching losses of IGBT  
 $V_{GE}=\pm 15V, R_{Gon}=3.3\Omega, R_{Goff}=3.3\Omega, V_{CE}=900V$

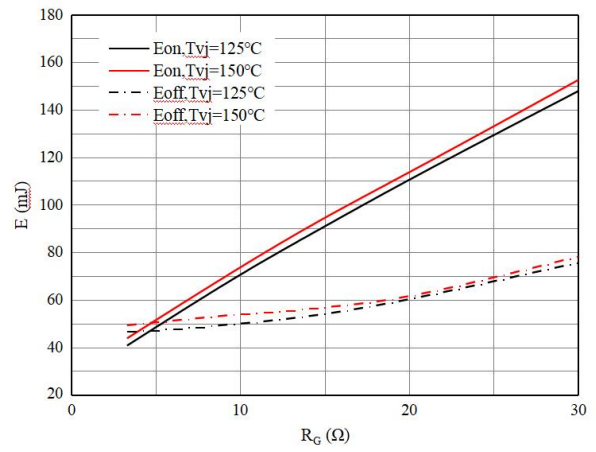


Fig 6. Switching losses of IGBT  
 $V_{GE}=\pm 15V, I_c=200A, V_{CE}=900V$

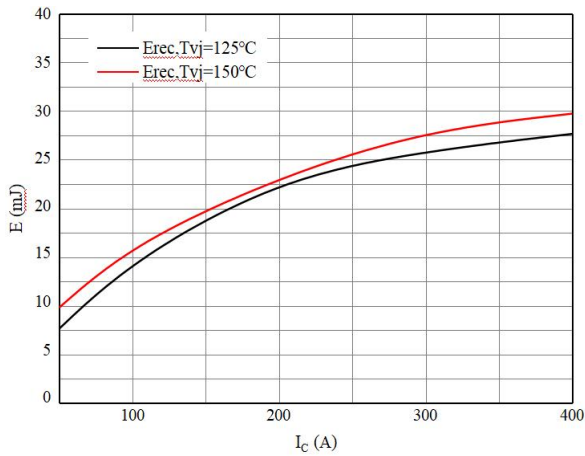


Fig 7. Switching losses of Diode  
 $R_{Gon}=3.3\Omega, V_{CE}=900V$

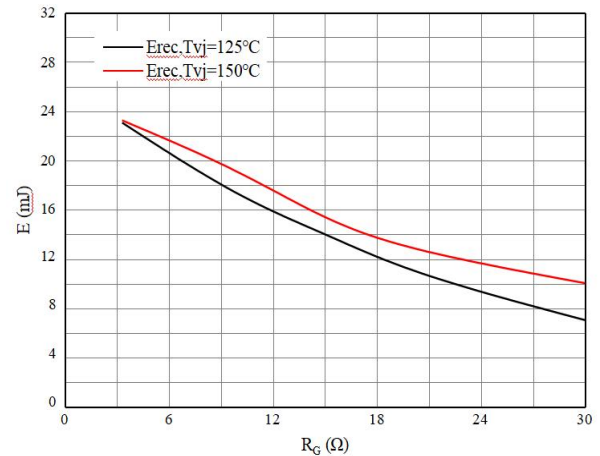


Fig 8. Switching losses of Diode  
 $I_F=200A, V_{CE}=900V$

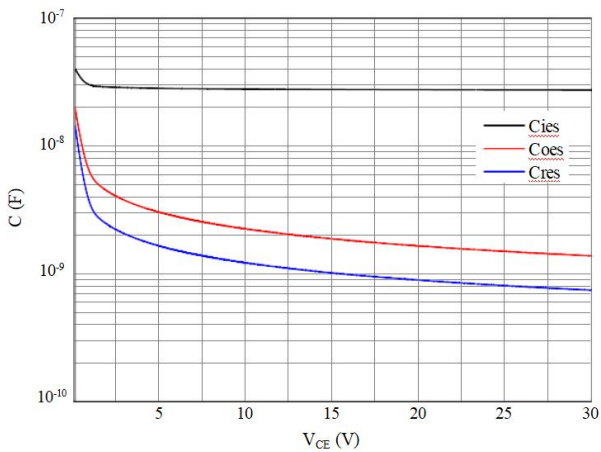
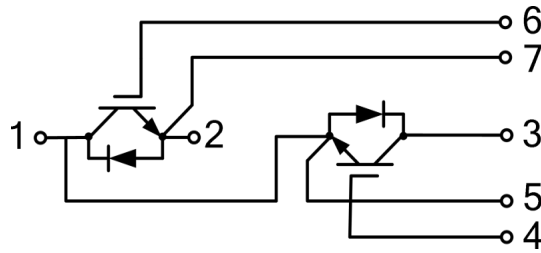
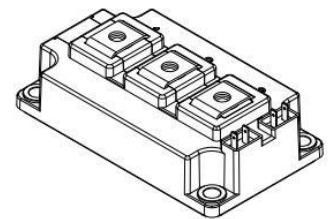
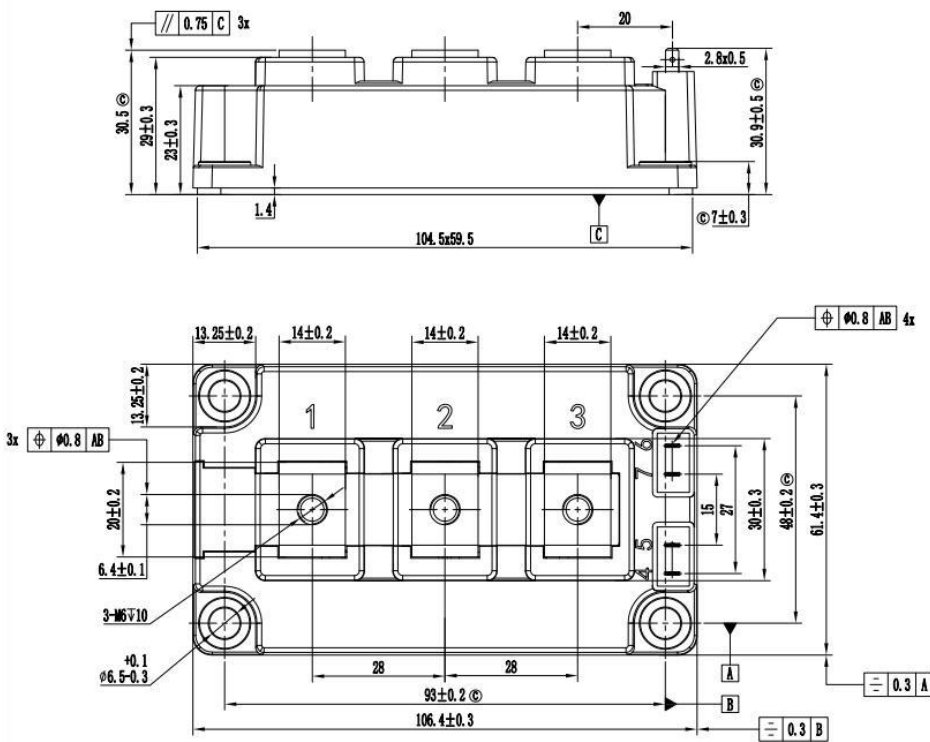


Fig 9. Capacitance characteristic

### Circuit Diagram



### Package Outlines(Unit: mm)



**\*Important Usage Information and Disclaimer**

The specifications of Zhuhai Hypersemi Co., Ltd. products are not guarantees of product characteristics. They reflect typical performance expected in standard applications, which may vary with specific uses. Users must conduct prior testing for their applications and make necessary adjustments.

Users are responsible for the safety of applications utilizing our products and must implement adequate safety measures to prevent physical injury, fire, or other risks in case of product failure. It is the user's duty to ensure that application designs comply with all applicable laws and standards. Our products must not be used in any applications where a product failure could reasonably result in personal injury, unless specifically authorized in a signed document by Zhuhai Hypersemi Co., Ltd.

No representations or warranties are made regarding the accuracy or completeness of this information, including any claims of non-infringement of third-party intellectual property rights. Zhuhai Hypersemi Co., Ltd. assumes no liability for any applications or uses of its products and does not grant any licenses to its intellectual property rights or those of others. We also make no claims regarding non-infringement of third-party intellectual property rights that may arise from applications.

Due to technical requirements, our products may contain hazardous substances. For details, please contact your nearest sales office. This document replaces all previous information and may be updated. We reserve the right to make changes.